



ABSTRACT

BURN-IN TESTING DEVICE

Disclosed is a novel burn-in socket comprising a carrier- and flexible circuit member assembly. The flexible circuit member has first and second electrically
5 conductive bumps formed on its opposite sides and an electric pattern or circuit formed thereon to make electric connections between the first and second bumps. The first bumps are adapted to abut on the exterior terminals of a semiconductor component such as a semiconductor bare chip or package to be set on the burn-in
10 socket. The second bumps are formed in the flexible circuit member in a position lateral to the first bumps and are so arranged that they may confront the electrically conductive contacts of the carrier in one-to-one correspondence, thereby permitting the second bumps to be put in electrical connection with the electrically conductive contacts of the carrier when the flexible circuit member is laid on the carrier.